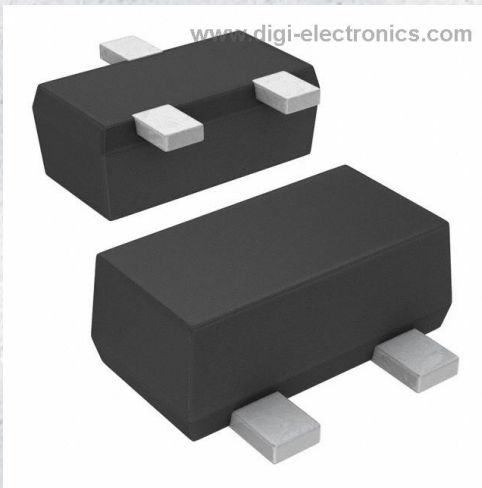


FJY3013R Datasheet



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	FJY3013R-DG
Manufacturer	onsemi
Manufacturer Product Number	FJY3013R
Description	TRANS PREBIAS NPN 50V SC89-3
Detailed Description	Pre-Biased Bipolar Transistor (BJT) NPN - Pre-Biased 50 V 100 mA 250 MHz 200 mW Surface Mount SC-89-3



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

FJY3013R

Series:

-

Transistor Type:

NPN - Pre-Biased

Voltage - Collector Emitter Breakdown (Max):

50 V

Resistor - Emitter Base (R2):

47 kOhms

Vce Saturation (Max) @ Ib, Ic:

300mV @ 500µA, 10mA

Frequency - Transition:

250 MHz

Mounting Type:

Surface Mount

Supplier Device Package:

SC-89-3

Manufacturer:

onsemi

Product Status:

Obsolete

Current - Collector (Ic) (Max):

100 mA

Resistor - Base (R1):

2.2 kOhms

DC Current Gain (hFE) (Min) @ Ic, Vce:

56 @ 5mA, 5V

Current - Collector Cutoff (Max):

100nA (ICBO)

Power - Max:

200 mW

Package / Case:

SC-89, SOT-490

Base Product Number:

FJY301

Environmental & Export classification

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

REACH Status:

REACH Unaffected

HTSUS:

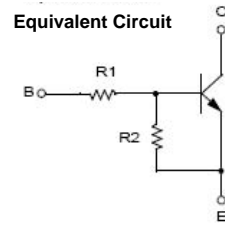
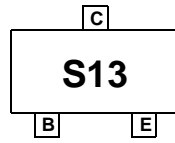
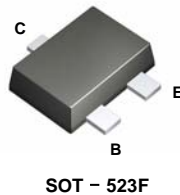
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FJY3013R

NPN Epitaxial Silicon Transistor

Features

- Switching circuit, Inverter, Interface circuit, Driver Circuit
- Built in bias Resistor (R1=2.2KΩ, R2=47KΩ)
- Complement to FJY4013R



Absolute Maximum Ratings* $T_a = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	50	V
V_{CEO}	Collector-Emitter Voltage	50	V
V_{EBO}	Emitter-Base Voltage	10	V
I_C	Collector Current	100	mA
T_{STG}	Storage Temperature Range	-55~150	$^\circ\text{C}$
T_J	Junction Temperature	150	$^\circ\text{C}$
P_C	Collector Power Dissipation, by $R_{\theta JA}$	200	mW

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics* $T_a = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	600	$^\circ\text{C/W}$

* Minimum land pad size.

Electrical Characteristics* $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	MIN	Typ	MAX	Units
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	$I_C = 10 \mu\text{A}, I_E = 0$	50			V
$V_{(BR)CEO}$	Collector-Base Breakdown Voltage	$I_C = 100 \mu\text{A}, I_B = 0$	50			V
I_{CBO}	Collector-Cutoff Current	$V_{CB} = 40 \text{V}, I_E = 0$			0.1	μA
h_{FE}	DC Current Gain	$V_{CE} = 5 \text{V}, I_C = 5 \text{mA}$	56			
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 10 \text{mA}, I_B = 0.5 \text{mA}$			0.3	V
f_r	Current Gain - Bandwidth Product	$V_{CE} = 10 \text{V}, I_C = 5 \text{mA}$		250		MHz
C_{cb}	Output Capacitance	$V_{CB} = 10 \text{V}, I_E = 0, f = 1.0 \text{MHz}$		3.7		pF
$V_{I(off)}$	Input Off Voltage	$V_{CE} = 5 \text{V}, I_C = 100 \mu\text{A}$	0.5			V
$V_{I(on)}$	Input On Voltage	$V_{CE} = 0.2 \text{V}, I_C = 5 \text{mA}$			1.1	V
R_1	Input Resistor		1.5	2.2	2.9	KΩ
R_1/R_2	Resistor Ratio		0.042	0.047	0.052	

* Pulse Test: $PW \leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$

Typical Performance Characteristics

Figure 1. DC current Gain

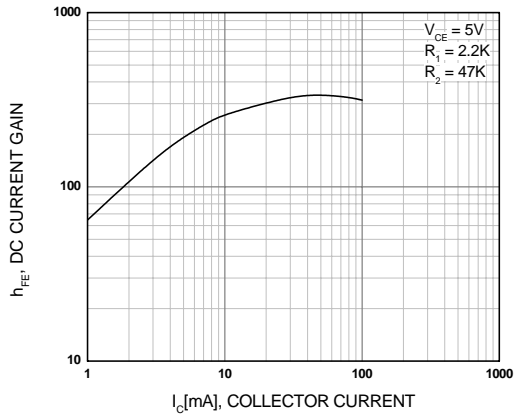


Figure 2. Input On Voltage

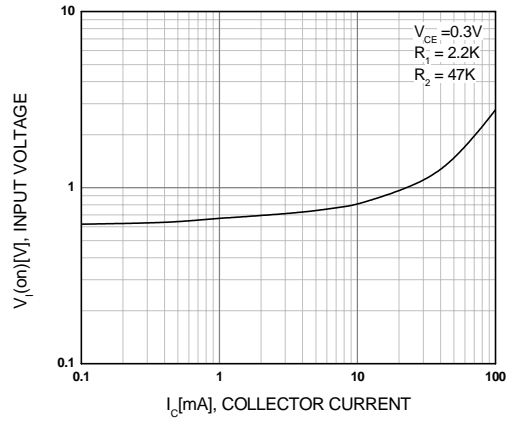


Figure 3. Collector-Emitter Saturation Voltage

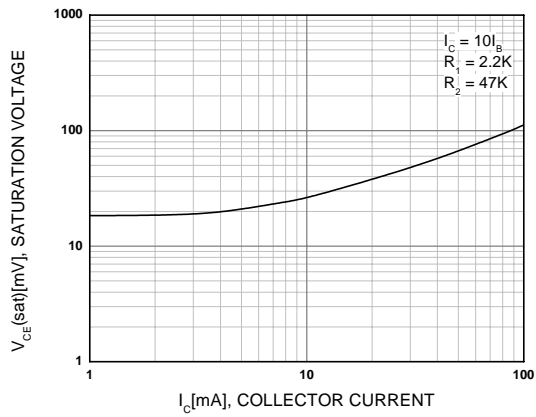
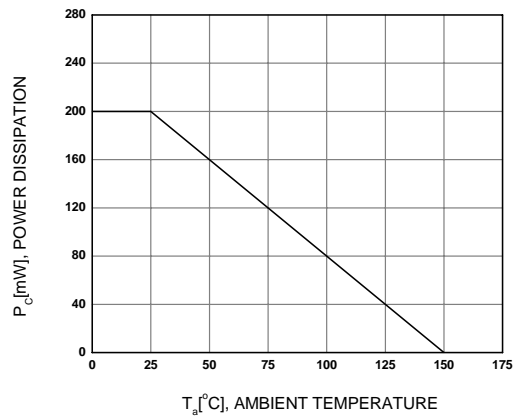
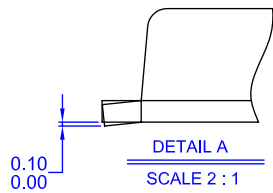
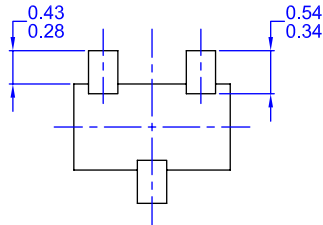
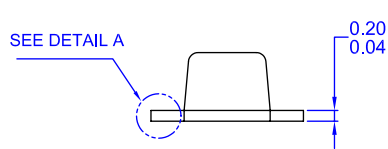
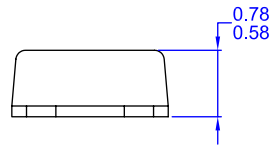
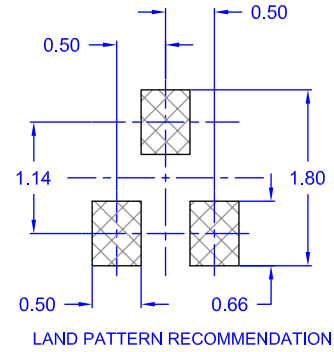
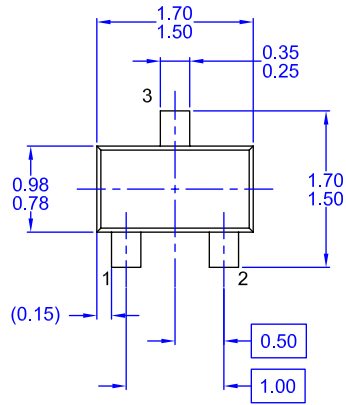


Figure 4. Power Derating



Package Dimensions

SOT-523F




- NOTES: UNLESS OTHERWISE SPECIFIED
 A) THIS PACKAGE CONFORMS TO EIAJ SC89 PACKAGING STANDARD.
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

Dimensions in Millimeters



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Rev. I25

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